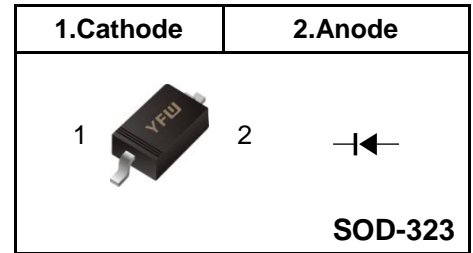


Small plastic SMD
package • Switching speed:
max. 50 ns • General
application

- Continuous reverse voltage: max. 200 V
- Repetitive peak reverse voltage: max. 250 V
- Repetitive peak forward current: max. 625 mA.

APPLICATIONS

- General purpose switching in e.g. surface mounted circuits.

Pinning

Marking Code

BAS321	A7
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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	250	V
V_R	continuous reverse voltage		–	200	V
I_F	continuous forward current	see Fig.2; note 1	–	250	mA
I_{FRM}	repetitive peak forward current	$t_p < 0.5 \text{ ms}$; $\delta \leq 0.25$	–	625	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25 \text{ }^\circ\text{C}$ prior to surge; see Fig.4			
		$t = 1 \text{ } \mu\text{s}$	–	9	A
		$t = 100 \text{ } \mu\text{s}$ $= 10 \text{ ms}$	–	3	A
P_{tot}	total power dissipation	$T_{amb} = 25 \text{ }^\circ\text{C}$; note 1	–	300	mW
T_{stg}	storage temperature		–65	+150	$^\circ\text{C}$
T_j	junction temperature		–	150	$^\circ\text{C}$

Note 1. Device mounted on an FR4 printed circuit-board.

CHARACTERISTICS
 $T_j = 25 \text{ }^\circ\text{C}$ unless otherwise specified.

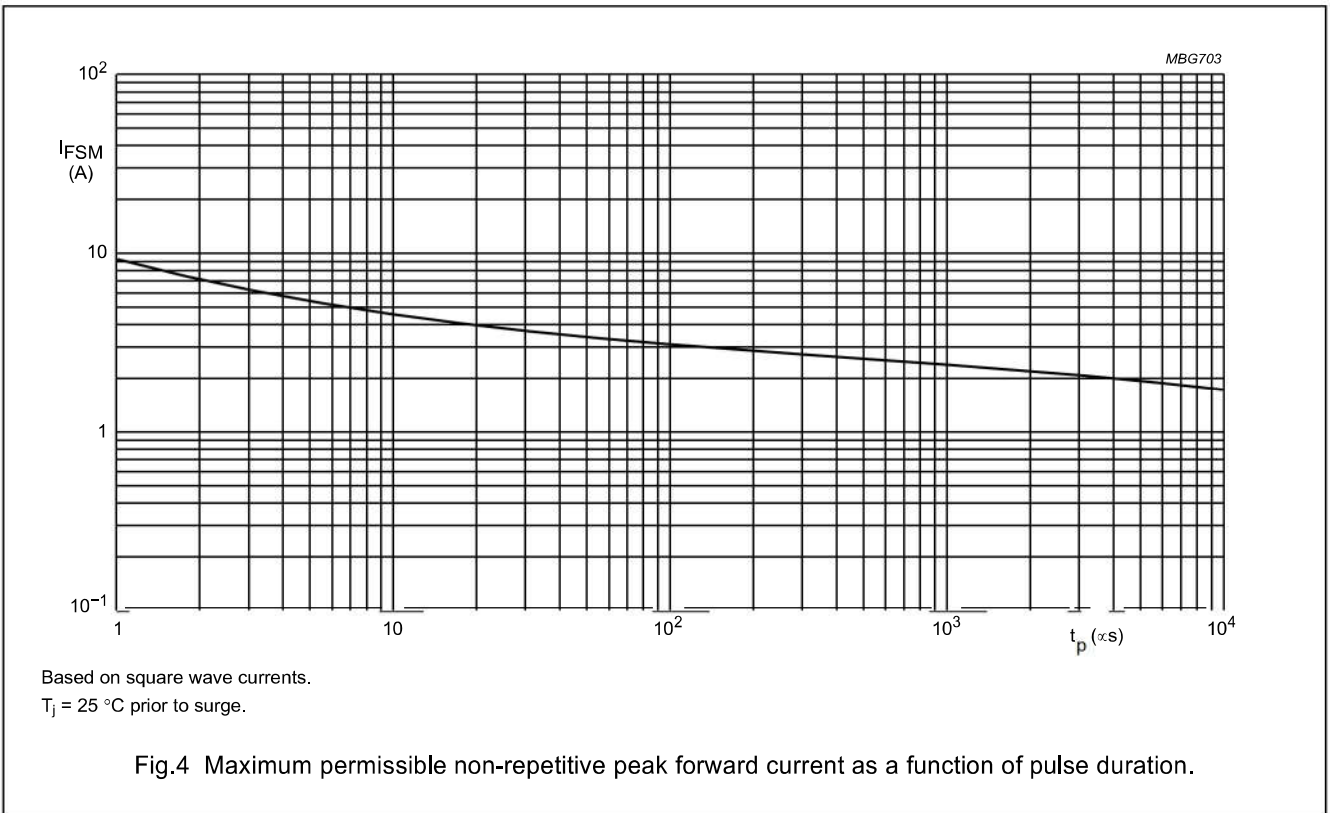
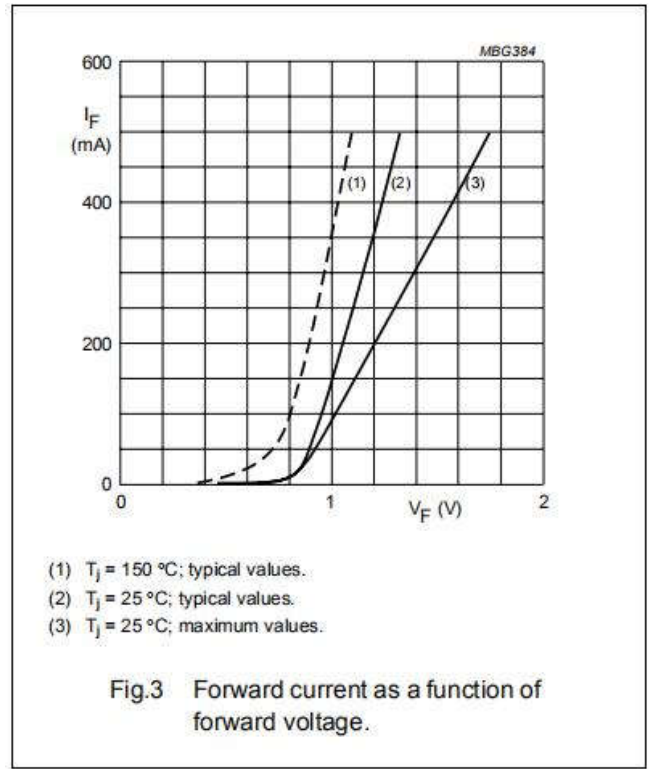
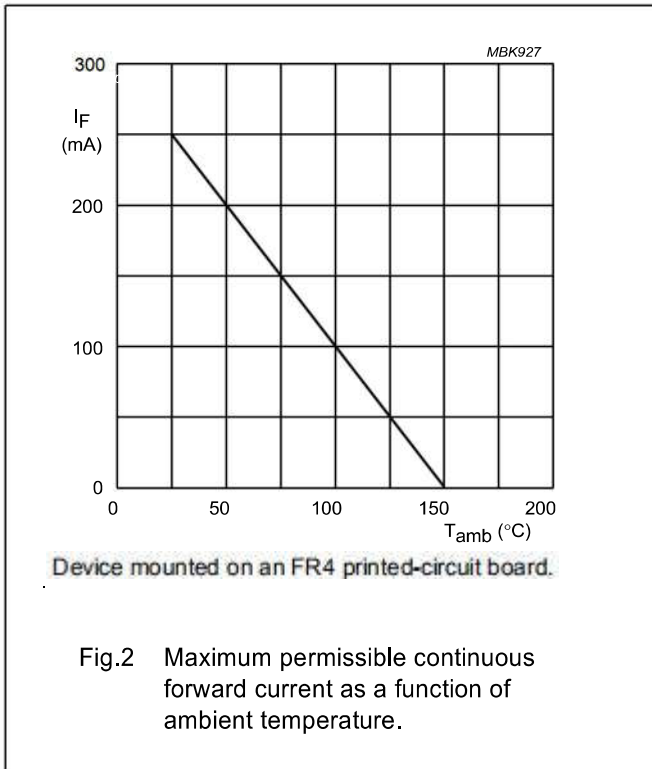
SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_F	forward voltage	see Fig.3		
		$I_F = 100 \text{ mA}$ $I_F = 200 \text{ mA}$	1 1.25	V V
I_R	reverse current	see Fig.5		
		$V_R = 200 \text{ V}$ $V_R = 200 \text{ V}$; $T_j = 150 \text{ }^\circ\text{C}$	100 100	nA μA
C_d	diode capacitance	$f = 1 \text{ MHz}$; $V_R = 0$; see Fig.6	2	pF
t_{rr}	reverse recovery time	when switched from $I_F = 30 \text{ mA}$ to $I_R = 30 \text{ mA}$; $R_L = 100 \text{ } \Omega$; measured at $I_R = 3 \text{ mA}$; see Fig.8	50	ns

THERMAL CHARACTERISTICS

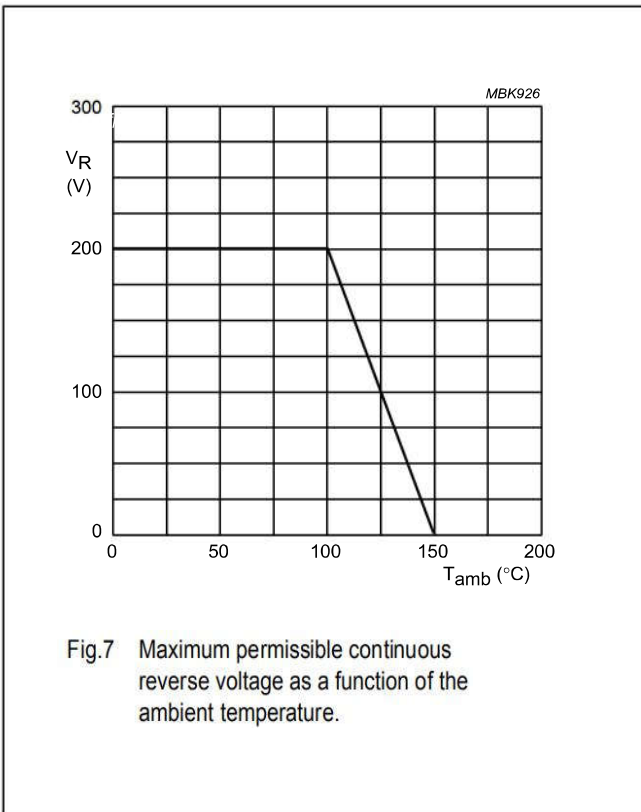
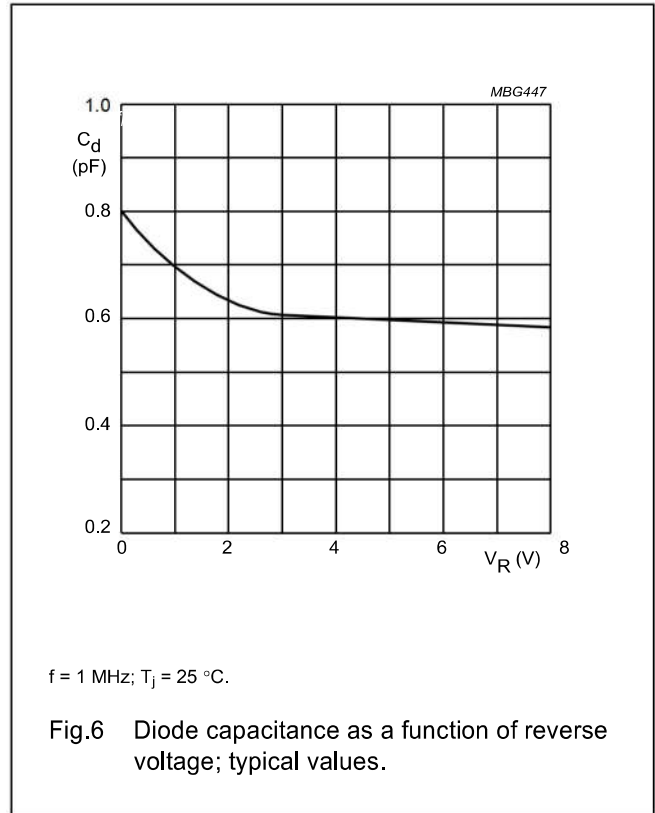
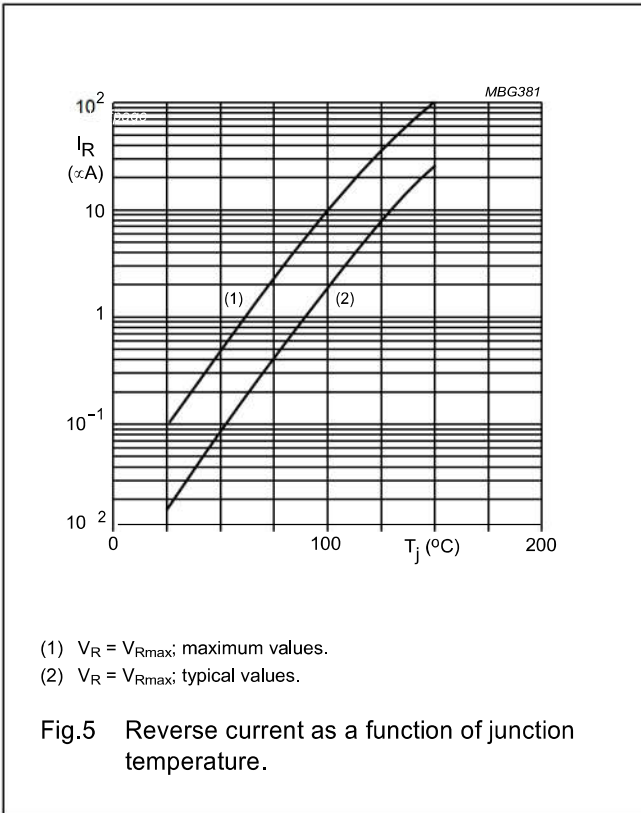
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to soldering point	$T_s = 90 \text{ }^\circ\text{C}$; note 1	130	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 2	366	K/W

- Notes**
1. Soldering point of cathode tab.
 2. Device mounted on an FR4 printed circuit board.

GRAPHICAL DATA



GRAPHICAL DATA



Ordering information

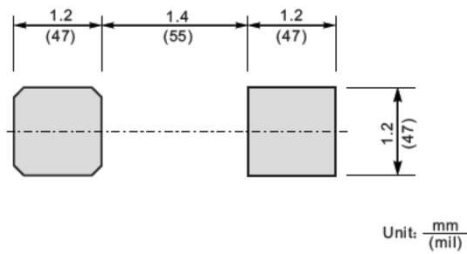
Package	Packing Description	Packing Quantity
SOD-323	Tape/Reel,7"reel	3000PCS/Reel 120000PCS/Carton

Package Dimensions

SOD-323

Dim.	Millimeter(mm)		mil	
	Min.	Max.	Min.	Max.
A	0.8	1.1	32	43
C	0.08	0.15	3.1	5.9
D	1.2	1.4	47	55
E	1.4	1.8	63	70
E1	2.55	2.75	100	108
b	0.25	0.4	9.8	16
L1	0.2	0.45	7.9	16
A1	-	0.2	-	8
∠	9°			

The recommended mounting pad size



Disclaimer

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